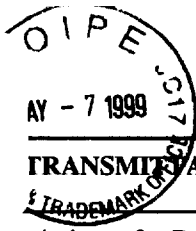


05-12-1999



5-7 99 mel



101034979

TRANSMITTAL OF DOCUMENT FOR RECORDATION PATENTS ONLY

Atty. Docket: 35.C13358

To the Assistant Commissioner for Patents: Please record the attached original documents or copy thereof.

<p>1. Name of conveying party(ies):</p> <p>SHIGEO KISO, ICHIRO KATAOKA, SATORU YAMADA, HIDENORI SHIOTSUKA and HIDEAKI ZENKO</p> <p>Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>	<p>2. Name and address of receiving party(ies):</p> <p>Name: <u>CANON KABUSHIKI KAISHA</u></p> <p>Foreign Address: <u>30-2, 3-chome, Shimomaruko, Ohta-ku</u> <u>Tokyo, Japan</u></p>
--	--

<p>3. Nature of conveyance:</p> <p><input checked="" type="checkbox"/> Assignment <input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Change of Name <input type="checkbox"/> Other _____</p> <p>Execution Date: <u>3/23/99; 3/24/99; 3/23/99; 3/23/99; 3/23/99</u></p>	<p>Domestic Address: _____</p> <p>City: _____ State _____ ZIP _____</p> <p>Additional name(s) & address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No</p>
--	---

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is: _____

<p>A. Patent Application Number: <u>09/256,227</u></p> <p>Filing Date: <u>February 24, 1999</u></p>	<p>B. Title of Invention: <u>ENCAPSULANT RESIN MEMBER FOR SEMICONDUCTOR AND SEMICONDUCTOR ELEMENT</u></p>
---	---

Additional numbers attached? Yes No

<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>Name: <u>Fitzpatrick, Cella, Harper & Scinto</u> <u>30 Rockefeller Plaza</u> <u>New York, New York 10112-3801</u></p> <p>Telephone No.: <u>(212) 218-2100</u></p> <p>Facsimile No.: <u>(212) 218-2200</u></p>	<p>6. Number of applications and patents involved: <u>One</u></p> <p>7. Total fee (37 CFR 3.41): . . \$ <u>40.00</u></p> <p><input checked="" type="checkbox"/> Enclosed <input type="checkbox"/> Authorized to be charged to deposit account</p> <p>8. Deposit account number (for deficiency or excess) <u>06-1205</u> (Attach duplicate copy of this page if paying by deposit account):</p>
---	---

05/12/1999 DNGUYEN 00000027 09256227
01. FC:581 (40.00 DP)

DO NOT USE THIS SPACE

9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and the attached is the original document or is a true copy of the original document.

<p><u>Leonard P. Diana</u> Name of Person Signing</p>	<p><u>Leonard P. Diana</u> Signature</p>	<p><u>May 6, 1999</u> Date</p>
--	---	-------------------------------------

Total number of pages including cover sheet, attachments, and documents: 2

ASSIGNMENT OF PATENT RIGHTS FOR THE UNITED STATES

FOR VALUE RECEIVED, WE, SHIGEO KISO, ICHIRO KATAOKA,
SATORU YAMADA, HIDENORI SHIOTSUKA and HIDEAKI ZENKO

citizens of JAPAN
residing respectively at

16-309, Tanabetorimoto, Kyotanabe-shi, Kyoto, Japan;
16-510, Tanabetorimoto, Kyotanabe-shi, Kyoto, Japan;
3-12-203, Tomiomoto-machi 2-chome, Nara-shi, Nara-ken, Japan;
16-504, Tanabetorimoto, Kyotanabe-shi, Kyoto, Japan; and
16-305, Tanabetorimoto, Kyotanabe-shi, Kyoto, Japan

hereby sell, assign, transfer and convey unto CANON KABUSHIKI KAISHA
a corporation of Japan

having a place of business at 30-2, Shimomaruko 3-chome, Ohta-ku, Tokyo, Japan

its successors, assigns and legal representatives (hereinafter called the "Assignee"), the entire right, title and interest, for
the United States, in and to certain inventions relating to ENCAPSULANT RESIN MEMBER FOR
SEMICONDUCTOR, AND SEMICONDUCTOR ELEMENT

and described in an application for Letters Patent of the United States filed by us on February 24, 1999
and which has been accorded Application No. 09/256,227

and in and to said application, and all divisions, renewals and continuations thereof, and all Letters Patent of the United
States which may be granted, thereon, and all reissues and extensions thereof; and we hereby authorize and request the
Commissioner for Patents and Trademarks of the United States to issue all Letters Patent upon said inventions to the
Assignee or to such nominees as it may designate.

AND we authorize and empower the said Assignee or nominees to invoke and claim for any application for
patent or other form of protection for said inventions, the benefit of the right of priority provided by the International
Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be
substituted for it, and to invoke and claim such right of priority without further written or oral authorization from us.

AND we hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any
assignment, consent to file or like document which may be required in the United States for any purpose and more
particularly in proof of the right of said Assignee or nominees to claim the aforesaid benefit of the right of priority
provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention
which may henceforth be substituted for it.

AND we hereby covenant that we have the full right to convey the entire right, title and interest herein assigned
and that we have not executed and will not execute any agreement in conflict herewith.

AND we hereby covenant and agree that we will communicate to said Assignee or nominees all facts known to
us pertaining to said inventions, and testify in all legal proceedings, sign all lawful papers, execute all divisional,
continuing and reissue applications, make all rightful oaths and declarations and in general perform all lawful acts
necessary or proper to aid said Assignee or nominees in obtaining, maintaining and enforcing all lawful patent protection
for said inventions in the United States.

By: Shigeo Kiso
SHIGEO KISO

Date: March 23, 1999

By: Ichiro Kataoka
ICHIRO KATAOKA

Date: March 24, 1999

By: Satoru Yamada
SATORU YAMADA

Date: March 23, 1999

By: Hidenori Shiotsuka
HIDENORI SHIOTSUKA

Date: March 23, 1999

By: Hideaki Zenko
HIDEAKI ZENKO

Date: March 23, 1999